What is claimed is:

1. A substrate comprising:

a first plurality of conductive pads disposed on a first side of the substrate, each conductive pad in the first plurality of conductive pads being configured to make electrical contact with a corresponding contact of a MicroSAS plug connector when the MicroSAS plug connector is mounted onto the substrate, there being a one-to-one correspondence between the contacts in the MicroSAS plug connector and the conductive pads in the first plurality of conductive pads; and

a different second plurality of conductive pads disposed on the first side of the substrate, each conductive pad in the second plurality of conductive pads being configured to make electrical contact with a corresponding contact of a MicroSATA plug connector when the MicroSATA plug connector is mounted onto the substrate, there being a one-to-one correspondence between the contacts in the MicroSATA plug connector and the conductive pads in the second plurality of conductive pads, at least one conductive pad belonging to both the first and second pluralities of conductive pads.

2. The substrate of claim 1 being a printed circuit board.

~~3. The substrate of claim 1, wherein each conductive pad in the first and second pluralities of conductive pad is connected to a different conductive trace disposed on the substrate.~~

34. The substrate of claim 1, wherein each conductive pad in the second plurality of conductive pads is also a conductive pad in the first plurality of conductive pads.

45. The substrate of claim 1, wherein the conductive pads in the first and second pluralities of conductive pads are arranged in first and second rows parallel to a first edge of the substrate, the first row being disposed between the first edge and the second row.

56. The substrate of claim 1, wherein each conductive pad in the first plurality of conductive pads is configured to make electrical contact with a corresponding contact of a straddle mount MicroSAS plug connector when the straddle mount MicroSAS plug connector is mounted onto the substrate.

67. The substrate of claim 1, wherein each conductive pad in the second plurality of conductive pads is configured to make electrical contact with a corresponding contact of a straddle mount MicroSATA plug connector when the straddle mount MicroSATA plug connector is mounted onto the substrate.

78. The substrate of claim 1, wherein each conductive pad in the first plurality of conductive pads is configured to make electrical contact with a corresponding contact of a low profile surface mount MicroSAS plug connector when the low profile surface mount MicroSAS plug connector is mounted onto the substrate.

89. The substrate of claim 1, wherein each conductive pad in the second plurality of conductive pads is configured to make electrical contact with a corresponding contact of a low profile surface mount MicroSATA plug connector when the low profile surface mount MicroSATA plug connector is mounted onto the substrate.

~~10. The substrate of claim 1, wherein each conductive pad in the first plurality of conductive pads is configured to make electrical contact with a corresponding contact of a standard profile surface mount MicroSAS plug connector when the standard profile surface mount MicroSAS plug connector is mounted onto the substrate.~~

~~11. The substrate of claim 1, wherein each conductive pad in the second plurality of conductive pads is configured to make electrical contact with a corresponding contact of a standard profile surface mount MicroSATA plug connector when the standard profile surface mount MicroSATA plug connector is mounted onto the substrate.~~

~~12. The substrate of claim 1, wherein each conductive pad in the first plurality of conductive pads is configured to make electrical contact with a corresponding contact of a right angle MicroSAS plug connector when the right angle MicroSAS plug connector is mounted onto the substrate.~~

~~13. The substrate of claim 1, wherein each conductive pad in the second plurality of conductive pads is configured to make electrical contact with a corresponding contact of a right angle MicroSATA plug connector when the right angle MicroSATA plug connector is mounted onto the substrate.~~

914. A plastic cover for covering at least portions of contact tails of a surface mount connector, the plastic cover comprising a top surface and a structured bottom surface

comprising a plurality of elongated spaced apart parallel ridges defining a plurality of elongated parallel channels therebetween, the channels extending from a front side of the plastic cover toward an opposite back side of the plastic cover, each channel corresponding to a different contact tail of the surface mount connector and being configured to cover the contact tail along at least a portion of a length of the contact tail, such that when the surface mount connector is mounted, the plastic cover is placed in a position so that the back side of the plastic cover is near and along a mounting face of the surface mount

connector resulting in each contact tail of the surface mount connector being housed within different channel.

1015. The plastic cover of claim 914, wherein at least two ridges in the plurality of elongated spaced apart parallel ridges have different widths.